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1. (Amended) A method to enhance integrated circuit device heat dissipation comprising the steps of:
- providing an integrated circuit device having a surface;
 - providing a flexible corrugated strip of a thermal conductive material having a flat flexible strip of a thermal conductive material bonded to one side thereto forming a single-faced flexible corrugated strip article; and
 - adhering the strip article to the surface of the integrated circuit device.

2. (Amended) The method of claim 1 wherein the strip is metal and is copper or aluminum.

4. (Amended) The method of claim 3 wherein the thickness of the strip used to make the corrugated strip and the flat flexible strip are both about 0.5 mil to 10 mil.

12. (Amended) The method of claim 1 wherein the flat flexible strip article has an adhesive thereon on the side to be adhered to the integrated circuit device.

13. (Amended) The method of claim 1 wherein the single-faced flexible corrugated strip article has a flat flexible strip of thermal conductive material bonded to the other side of the flexible corrugated strip forming a double-faced flexible corrugated strip.

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6. (Amended) A method to enhance integrated circuit device heat dissipation comprising the steps of:
- providing an integrated circuit device having a surface;
- providing a strip of flexible flat thermal conductive material;
- forming corrugations in the flexible thermal conductive material;
- bonding a thermal conductive material flat strip to one side of the flexible corrugated strip forming a single-faced flexible corrugated strip article; and
- adhering the single-faced flexible corrugated strip to the surface of the integrated circuit device.

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20. (Amended) The method of claim 16 wherein an adhesive is applied to the side of the single-faced corrugated strip article to be adhered to the integrated circuit device.

21. (Amended) The method of claim 16 wherein a second flexible strip thermal conductive material is bonded to the other side of the corrugated flexible thermal conductive material forming a double-faced corrugated strip article.

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24. (Amended) An article of manufacture for dissipating heat for integrated circuit devices comprising a corrugated flexible strip of thermal conductive material having a flat flexible strip of a thermal conductive material bonded to one side thereto forming a single-faced flexible corrugated strip article.

1 27. (Amended) The article of claim 24 wherein the flat strip of thermal conductive
2 material has an adhesive on the side to be adhered to an integrated circuit device.

1 28. (Amended) The article of claim 24 wherein a second flat flexible strip of thermal
2 conductive material is bonded to the other side of the corrugated material to form a
3 double-faced flexible corrugated strip article.